

Comments and Corrections

Corrections to “Multifunction Thermopile Sensors Fabricated With a MEMS-Compatible Process”

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In the above paper [1], the following changes should have been reflected in the final, published work, but were not.

The first footnote should read:

Manuscript received November 14, 2012; revised January 31, 2013; accepted March 4, 2013. This work was supported by the National Science Council of Taiwan under Grants NSC 98-2221-E-002-090, NSC 99-2628-E-002-004, NSC 100-2628-E-002-002, and NSC 101-2221-E-002-056-MY3, and Excellent Research Projects of National Taiwan University, under Grants 98R0062-07, 99R80300, 99R80306, 99R80203, 10R80919-1, AE01-01 (101R89081), and 102R89084. This paper was recommended by Associate Editor A. Diebold.

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The word “temperature” was misspelled on pages 3 and 4.

In Section III-B, the last paragraph should read:

We define the sensitivity to CO₂ partial pressure change as, again, the slope of the curve (absolute value taken). The non-overlap-type elongated thermopile sensor exhibits the highest sensitivity (Fig. 9).

Reference [10] should have appeared as:

[10] S.-H. Tseng, C.-L. Fang, P.-C. Wu, Y.-Z. Juang, and M. S.-C. Lu, “A CMOS MEMS thermal sensor with high frequency output,” in *Proc. IEEE Sensors 2008*, Oct. 2008, pp. 387–390.

Reference [14] should have appeared as:

[14] K. P. Yoo, H. P. Hong, M. J. Lee, S. J. Min, C. W. Park, W. S. Choi, and N. K. Min, “Fabrication, characterization and application of a microelectromechanical system (MEMS) thermopile for non-dispersive infrared gas sensors,” *Meas. Sci. Technol.*, vol. 22, no. 11, 115206, Nov. 2011.

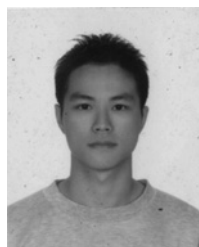
Chia-feng Chou’s biography should have appeared as:



Chia-feng Chou received the B.S. degree in electrophysics from National Chiao Tung University (NCTU), Hsinchu, Taiwan, in 2008, and the M.S. degree from the Graduate Institute of Photonics and Optoelectronics, National Taiwan University (NTU), Taipei, Taiwan, in 2013.

His current research interests include MEMS thermocouples.

Jia-qi Hong’s biography should have appeared as:



Jia-qi Hong received the B.S. degree in engineering and system science from National Tsing Hua University (NTHU), Hsinchu, Taiwan, in 2005, and the M.S. degree from the Graduate Institute of Photonics and Optoelectronics, National Taiwan University (NTU), Taipei, Taiwan, in 2009.

His current research interests include MEMS thermoelectric batteries and MEMS thermocouples/thermopiles.

Jui-che Tsai’s biography should have appeared as:



Jui-che Tsai (M’09) received the B.S. degree in electrical engineering from National Taiwan University (NTU), Taipei, Taiwan, in 1997, the M.S. degree in electro-optical engineering from the Graduate Institute of Electro-Optical Engineering [currently named Graduate Institute of Photonics and Optoelectronics (GIPO)], NTU, in 1999, and the Ph.D. degree in electrical engineering from the University of California, Los Angeles, USA, in 2005.

From 1999 to 2001, he was a Second Lieutenant in the military. Before joining the faculty of NTU, he was a Post-Doctoral Researcher with the Department of Electrical Engineering and Computer Sciences and the Berkeley Sensor and Actuator Center (BSAC), University of California, Berkeley, CA, USA. He is currently an Associate Professor with the Graduate Institute of Photonics and Optoelectronics and the Department of Electrical Engineering, NTU. His current research interests include optical microelectromechanical systems (MEMS), MEMS technologies, optical fiber communication, and biophotonics.

REFERENCES

- [1] L.-M. Sin, T.-T. Pan, C.-W. Tsai, C.-F. Chou, J.-Q. Hong, and J.-C. Tsai, “Multifunction thermopile sensors fabricated with a MEMS-compatible process,” *IEEE Trans. Semicond. Manuf.*, vol. 26, no. 2, pp. 242–247, May 2013.